

**PATENT ASSIGNMENT**

Electronic Version v1.1  
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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT						
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT						
<b>CONVEYING PARTY DATA</b>							
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Osamu Machida</td> <td>12/20/2007</td> </tr> <tr> <td>Akio Iwabuchi</td> <td>12/20/2007</td> </tr> </tbody> </table>		Name	Execution Date	Osamu Machida	12/20/2007	Akio Iwabuchi	12/20/2007
Name	Execution Date						
Osamu Machida	12/20/2007						
Akio Iwabuchi	12/20/2007						
<b>RECEIVING PARTY DATA</b>							
<b>Name:</b>	Sanken Electric Co., Ltd.						
<b>Street Address:</b>	3-6-3, Kitano,						
<b>City:</b>	Niiza-shi, Saitama						
<b>State/Country:</b>	JAPAN						
<b>PROPERTY NUMBERS Total: 1</b>							
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12015067</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12015067		
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Application Number:	12015067						
<b>CORRESPONDENCE DATA</b>							
<b>Fax Number:</b>	(215)568-3439						
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>							
<b>Phone:</b>	2155683100						
<b>Email:</b>	clausz@woodcock.com						
<b>Correspondent Name:</b>	Michael P. Dunnam, Esquire						
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<b>Address Line 2:</b>	2929 Arch Street						
<b>Address Line 4:</b>	Philadelphia, PENNSYLVANIA 19104						
<b>ATTORNEY DOCKET NUMBER:</b>	TAK-0443						
<b>NAME OF SUBMITTER:</b>	Gina Clausz						
<b>Total Attachments: 1</b> source=assignment#page1.tif							

CH \$40.00 12015067

# Assignment

FOR VALUE RECEIVED OSAMU MACHIDA and AKIO IWABUCHI

subject of Japan residing respectively at Japan

hereby sell, assign, transfer and convey unto

Sanken Electric Co., Ltd.

a corporation of Japan

having a place of business at 3-6-3, Kitano, Niiza-shi, Saitama Japan

(hereinafter called the "Assignee"), its successors, assigns and legal representatives, the entire right, title and interest, for all countries, in and to certain inventions relating to

## DIODE-LIKE COMPOSITE SEMICONDUCTOR DEVICE

and described in an application for Letters Patent of the United States executed by US on December 20, 2007

and in and to said application, and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues and extensions thereof, and all applications for Letters Patent which may be filed, and all Letters Patent which may be granted, upon said inventions in any countries foreign to the United States, and all reissues, renewals and extensions thereof; and WE hereby authorize and request the Commissioner of Patents of the United States, and all officials of countries foreign to the United States having authority so to do, to issue all Letters Patent upon said inventions to the Assignee, its successors, assigns or legal representatives or to such nominee as it may designate.

AND WE authorize and empower the said Assignee, its successors, assigns and legal representatives or nominees, to invoke and claim for any application for patent or other form of protection for said inventions filed by it or them, the benefit of the right of priority provided by the International Convention for the Protection of Industrial Property, as amended, or by any convention which may henceforth be substituted for it, and to invoke and claim such right of priority without further written or oral authorization from

AND WE hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any assignment, consent to file or like document which may be required in any country for any purpose and more particularly in proof of the right of the said Assignee or nominee to claim the aforesaid benefit of the right of priority provided by the International Convention for the Protection of Industrial Property, as amended, or by any convention which may henceforth be substituted for it.

AND WE hereby covenant that WE have the full right to convey the entire right, title and interest herein assigned and that we have not executed and will not execute any agreement in conflict herewith.

AND WE hereby covenant and agree that WE will communicate to said Assignee, its successors, assigns and legal representatives, all facts known to US pertaining to said inventions, and testify in all legal proceedings, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths, and in general perform all lawful acts necessary or proper to aid said Assignee, its successors, assigns and legal representatives or nominee in obtaining, maintaining and enforcing lawful patent protection for said inventions in any and all countries.

IN WITNESS WHEREOF, we hereunto set our hand and seal  
this 20th day of December, 2007.

Osamu Machida  
Osamu Machida  
Akio Iwabuchi  
Akio Iwabuchi

Witness: Hirohiko Kimura  
Hirohiko Kimura

Address: c/o Sanken Electric Co., Ltd., of 3-6-3, Kitano, Niiza-shi, Saitama Japan

Witness: Noritsugu Takano  
Noritsugu Takano

Address: 427-12, Ushiko, Kawagoe-shi, Saitama-ken, Japan.